

L Number	Hits	Search Text	DB	Time stamp
1	3	chip SAME ((heat thermal) NEAR transmiss\$4 NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:45
2	9	chip AND ((heat thermal) NEAR transmiss\$4 NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
3	883	chip AND ((heat thermal) NEAR transmiss\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
4	163	chip WITH ((heat thermal) NEAR transmiss\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
5	27	(chip WITH ((heat thermal) NEAR transmiss\$4)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
6	13	("5355283" "5583378" "5616958" "5751060" "5777386" "5817545" "5834839" "5866949" "5883430" "5896271" "5898224" "6137164" "6225699").PN.	USPAT	2004/02/12 08:56
7	5	("5404273" "5510956" "5619070" "5625226" "5672548").PN.	USPAT	2004/02/12 09:03

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1	3	chip SAME ((heat thermal) NEAR transmis\$4 NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:45
2	9	chip AND ((heat thermal) NEAR transmis\$4 NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
3	883	chip AND ((heat thermal) NEAR transmis\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
4	163	chip WITH ((heat thermal) NEAR transmis\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
5	27	(chip WITH ((heat thermal) NEAR transmis\$4)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
6	13	("5355283" "5583378" "5616958" "5751060" "5777386" "5817545" "5834839" "5866949" "5883430" "5896271" "5898224" "6137164" "6225699").PN.	USPAT	2004/02/12 08:56
7	5	("5404273" "5510956" "5619070" "5625226" "5672548").PN.	USPAT	2004/02/12 09:03

L Number	Hits	Search Text	DB	Time stamp
4	9	(chip die) NEAR5 (electrically NEAR connect\$3) NEAR5 (tie NEAR bar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 17:32
5	62	(chip die) WITH (electrically NEAR connect\$3) WITH (tie NEAR bar)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 17:40
6	4	((chip die) WITH (electrically NEAR connect\$3) WITH (tie NEAR bar)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 18:12
7	53	(chip die) WITH (electrically NEAR connect\$3) WITH (tie NEAR bar) WITH lead\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 17:41
8	1	(chip die) WITH (electrically NEAR connect\$3) WITH (tie NEAR bar) WITH lead\$1 WITH (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 17:46
9	5	("5202752" "5216278" "5306949" "5444294" "5508563").PN.	USPAT	2004/02/12 17:45
10	0	(flip NEAR chip) WITH (electrically NEAR connect\$3) WITH (tie NEAR bar) WITH lead\$1 WITH (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 17:46
11	4	chip WITH (tie NEAR bar) WITH lead\$1 WITH (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 18:02
12	27	chip SAME (tie NEAR bar) SAME lead\$1 SAME (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 18:11
13	427	(die NEAR pad\$3) WITH (tie NEAR bar\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 18:12
14	39	((die NEAR pad\$3) WITH (tie NEAR bar\$1)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 18:12
15	2	("5885852" "6177719").PN.	USPAT	2004/02/12 18:24
-	3	chip SAME ((heat thermal) NEAR transmis\$4 NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:45
-	9	chip AND ((heat thermal) NEAR transmis\$4 NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49

-	883	chip AND ((heat thermal) NEAR transmis\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
-	163	chip WITH ((heat thermal) NEAR transmis\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 09:19
-	27	(chip WITH ((heat thermal) NEAR transmis\$4)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 08:49
-	13	("5355283" "5583378" "5616958" "5751060" "5777386" "5817545" "5834839" "5866949" "5883430" "5896271" "5898224" "6137164" "6225699").PN.	USPAT	2004/02/12 08:56
-	5	("5404273" "5510956" "5619070" "5625226" "5672548").PN.	USPAT	2004/02/12 09:03
-	5	(flip NEAR chip) WITH ((heat thermal) NEAR transmis\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 09:21
-	10	(flip NEAR chip) same ((heat thermal) NEAR transmis\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:21
-	2	("6331451").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:24
-	2	("6314639").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:25
-	328	(bump\$1 (solder NEAR ball\$1)) WITH (thermal\$2 NEAR conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:44
-	150	((bump\$1 (solder NEAR ball\$1)) WITH (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:45
-	29	((((bump\$1 (solder NEAR ball\$1)) WITH (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)) and (lead NEAR frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:45
-	9	("5814881" "6080264" "6087718" "6087722" "6118176" "6261865" "6297547" "6307257" "6337521").PN.	USPAT	2004/02/12 11:37
-	175	(bump\$1 (solder NEAR ball\$1)) NEAR5 (thermal\$2 NEAR conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:45

-	20	((bump\$1 (solder NEAR ball\$1)) NEAR5 (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)) and (lead NEAR frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:54
-	91	((bump\$1 (solder NEAR ball\$1)) NEAR5 (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:47
-	368	(heat\$3 thermal\$2) NEAR transmi\$5 NEAR (layer\$1 film\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:53
-	1	((heat\$3 thermal\$2) NEAR transmi\$5 NEAR (layer\$1 film\$1)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 14:55
-	6311	(heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:01
-	240	((heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:54
-	51	((heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1)) and (flip NEAR chip)) and (lead NEAR frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:54
-	7	(flip NEAR chip) WITH ((heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:02

-	29	((bump\$1 (solder NEAR ball\$1)) WITH (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)) and (lead NEAR frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:45
-	9	("5814881" "6080264" "6087718" "6087722" "6118176" "6261865" "6297547" "6307257" "6337521").PN.	USPAT	2004/02/12 11:37
-	175	(bump\$1 (solder NEAR ball\$1)) NEAR5 (thermal\$2 NEAR conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 11:45
-	20	((bump\$1 (solder NEAR ball\$1)) NEAR5 (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)) and (lead NEAR frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:54
-	91	((bump\$1 (solder NEAR ball\$1)) NEAR5 (thermal\$2 NEAR conduct\$3)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:47
-	368	(heat\$3 thermal\$2) NEAR transmi\$5 NEAR (layer\$1 film\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:53
-	1	((heat\$3 thermal\$2) NEAR transmi\$5 NEAR (layer\$1 film\$1)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:53
-	6311	(heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:01
-	240	((heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1)) and (flip NEAR chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:54
-	51	((heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1)) and (flip NEAR chip)) and (lead NEAR frame)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 12:54
-	7	(flip NEAR chip) WITH ((heat\$3 thermal\$2) NEAR (conduct\$3 transmi\$5) NEAR (layer\$1 film\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/12 13:02